

<b>PCN Number:</b>	20230209000.1	<b>PCN Date:</b>	February 09, 2023
<b>Title:</b>	Qualification of DMOS6 as an additional Fab site option for select LBC9 devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 9, 2023	<b>Sample requests accepted until:</b>	Mar 9, 2023*

**\*Sample requests received after March 9, 2023 will not be supported.**

<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

**PCN Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of its DMOS6 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
RFAB	LBC9	300mm	DMOS6	LBC9	300mm

Qual details are provided in the Qual Data Section.

**Reason for Change:**

Continuity of supply.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
<b>DMOS6</b>	<b>DM6</b>	<b>USA</b>	<b>Dallas</b>

Sample product shipping label (not actual product label)

**Product Affected:**

TLV62568ADRLR	TLV62568APDRLR	TLV62569ADRLR	TLV62569APDRLR
TLV62568ADRLT	TLV62568APDRLT	TLV62569ADRLT	TLV62569APDRLT

## Qualification Report

Approve Date 02-Feb-2023

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV62568APDRLR	QBS Process Reference: TLV62569DBVR	QBS Product and Package Reference: BQ25150YFPT
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	3/3000/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	3/9/0	-
CDM	ESD - CDM	500 V	1/3/0	3/9/0	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
LU	Latch-up (per JESD78)		1/6/0	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0

- QBS: Qual By Similarity

- Qual Device TLV62568APDRLR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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